Product Change Notification

111854 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**111854 - 01**
Change Title:	**Intel® 82574IT Gigabit Ethernet Controller (Hartwell) Tape &Reel WG82574IT MM#898555,** **Tray WG82574IT MM#898556,** **Intel® 82574L Gigabit Ethernet Controller (Harwell) Tape & Reel WG82574L MM#898552,** **Tray WG82574L MM#898553,** **Intel® 82583V Gigabit Ethernet Controller (Colleyville) Tape & Reel WG82583V MM#903008,** **Tray WG82583V MM#903072** **PCN 111854-01** **Product Material** **Ethernet Controller wire bond material is changing from Gold (Au) to Copper Palladium (Cu-Pd)** **Reason for Revision: Update cutover manufacturing date code from 1322 to 1318**
Date of Publication:	**July 08, 2013**

Key Characteristics of the Change:
Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jun 07, 2013

Description of Change to the Customer:

Reason for Revision: Update cutover manufacturing date code as referenced below:

Before: Manufacturing Date Code WW1322

After: Manufacturing Date Code WW1318

The Intel Gigabit Ethernet Controllers, noted within the affected products table within this PCN notice, will have a wire bond material change from Gold (AU) to Copper Palladium (Cu-PD).

1. Package Bond wire changed from 99.99% Au 0.8mil to Pd-Cu, 0.7mil
2. Package molding Compound changed from 9220HF to EME-G631SB

Specifics of the change are:

- With recent advancements made in copper bonding, most of the assembly suppliers are switching to Cu-Pd as mainstream bonding process. Intel is following the High Volume Manufacturing (HVM) trend.
- Cu-Pd products are one-to-one pin compatible with Au products and there is no form, fit, or function change.
- See "Products Affected/Intel Ordering Codes" table below for marketing name, s-spec and MM#s.
- The products with the new wire material have identical quality and reliability as the current products.

Customer Impact of Change and Recommended Action:

There are no changes to form, fit or function. The Cu-Pd and Au parts are totally compatible with each other. Customers do not need to do anything different in the receipt and use of the Cu-Pd products in their manufacturing process.

- Intel is moving with the rest of the industry per JEDEC standards.
- There are no changes to form, fit or function.
- The Cu-Pd and Au parts are totally compatible with each other.
- Customers do not need to do anything different in the receipt and use of the Cu-Pd products in their manufacturing process.
- Customers could get gold wire or copper palladium wire products until inventory is depleted.
- Components with date code greater than **1318** will have Cu-PD.
- Customers can obtain a customer ready qualification report from their local Intel Field Sales Representative or their Intel CQE (Customer Quality Engineer).

Products Affected / Intel Ordering Codes:

Marketing Name	Stepping	Product Code	S-Spec	MM#
Intel® 82574L Gigabit Ethernet Controller (Hartwell) Tape & Reel	A1	WG82574L	S LBA8	898552
Intel® 82574L Gigabit Ethernet Controller(Hartwell) Tray	A1	WG82574L	S LBA9	898553
Intel® 82574IT Gigabit Ethernet Controller(Hartwell) Tape and Reel	A1	WG82574IT	S LBAB	898555
Intel® 82574IT Gigabit Ethernet Controller(Hartwell) Tray	A1	WG82574IT	S LBAC	898556
Intel® 82583V Gigabit Ethernet Controller(Colleyville) Tape & Reel	A1	WG82583V	S LGVC	903008
Intel® 82583V Gigabit Ethernet Controller(Colleyville) Tray	A1	WG82583V	S LGVD	903072

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
March 8, 2013	00	Originally Published PCN
July 08, 2013	01	Update cutover manufacturing date code